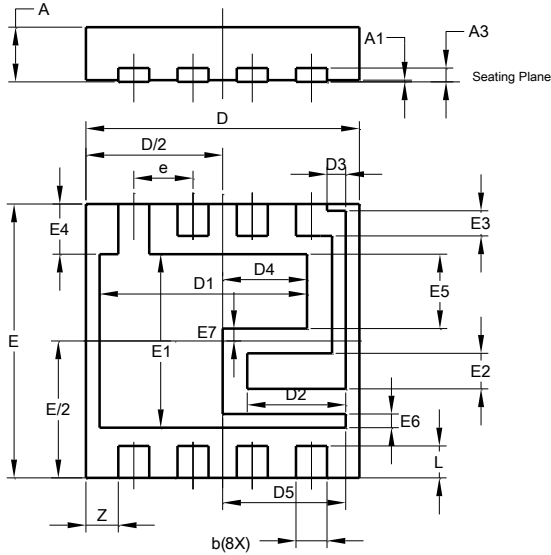


Package Outline Dimensions

U-DFN3030-8 (Type D)

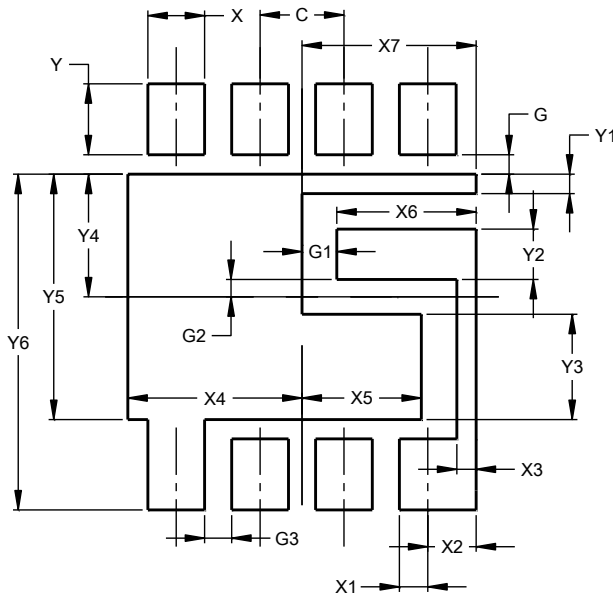


U-DFN3030-8 Type D							
Dim	Min	Max	Typ	Dim	Min	Max	Typ
A	0.570	0.630	0.600	E	2.950	3.075	3.000
A1	0	0.050	0.020	E1	1.800	2.000	1.900
A3	-	-	0.150	E2	0.290	0.490	0.390
b	0.290	0.390	0.340	E3	0.175	0.375	0.275
D	2.950	3.075	3.000	E4	-	-	0.550
D1	2.175	2.375	2.275	E5	-	-	0.815
D2	0.980	1.180	1.080	E6	-	-	0.150
D3	0.105	0.305	0.205	E7	-	-	0.135
D4	-	-	0.925	L	0.300	0.40	0.350
D5	-	-	1.330	Z	-	-	0.355
e	-	-	0.650				

All Dimensions in mm

Suggested Pad Layout

U-DFN3030-8 (Type D)



Dimensions	Value (in mm)
C	0.650
G	0.150
G1	0.270
G2	0.135
G3	0.210
X	0.440
X1	0.220
X2	0.375
X3	0.150
X4	1.350
X5	0.925
X6	1.080
X7	1.350
Y	0.550
Y1	0.150
Y2	0.390
Y3	0.815
Y4	0.950
Y5	1.900
Y6	2.600

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.